

μPA2826T1S

N-channel MOSFET

20 V , 27 A , 4.3 m Ω

R07DS0989EJ0100 Rev.1.00 Dec 25, 2012

Description

The μ PA2826T1S is N-channel MOS Field Effect Transistor designed for power management applications of portable equipment .

Features

- $V_{DSS} = 20 \text{ V } (T_A = 25^{\circ}\text{C})$
- Low on-state resistance
 - --- $R_{DS(on)}$ = 4.3 mΩ MAX. (V_{GS} = 8.0 V, I_{D} = 13.5 A)
- 2.5 V Gate-drive available
- Small & thin type surface mount package with heat spreader
- Pb-free and Halogen free



HWSON-8

Ordering Information

Part No.	LEAD PLATING	PACKING	Package
μ PA2826T1S-E2-AT* ¹	Pure Sn(Tin)	Tape 5000 p/reel	HWSON-8
			0.022 g TYP.

Note: *1. Pb-free (This product does not contain Pb in external electrode and other parts.)

Absolute Maximum Ratings ($T_A = 25$ °C)

Item	Symbol	Ratings	Unit
Drain to Source Voltage (V _{GS} = 0 V)	V _{DSS}	20	V
Gate to Source Voltage (V _{DS} = 0 V)	V _{GSS}	±12	V
Drain Current (DC) (T _C = 25°C)	I _{D(DC)}	±27	Α
Drain Current (pulse) *1	I _{D(pulse)}	±81	Α
Total Power Dissipation *2	P _{T1}	1.5	W
Total Power Dissipation (PW = 10 sec) *2	P _{T2}	3.8	W
Total Power Dissipation (T _C = 25°C)	P _{T3}	20	W
Channel Temperature	T _{ch}	150	°C
Storage Temperature	T _{stg}	−55 to +150	°C

Thermal Resistance

Channel to Ambient Thermal Resistance *2 R_{th(ch-A)} 83.3 °C/W Channel to Case(Drain) Thermal Resistance R_{th(ch-C)} 6.25 °C/W

Notes: *1. PW \leq 10 μ s, Duty Cycle \leq 1%

*2. Mounted on a glass epoxy board of 25.4 mm x 25.4 mm x 0.8 mmt

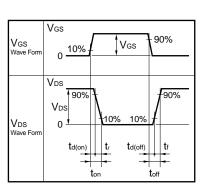
Electrical Characteristics ($T_A = 25^{\circ}C$)

Item	Symbol	MIN.	TYP.	MAX.	Unit	Test Conditions
Zero Gate Voltage Drain Current	I _{DSS}			1	μΑ	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$
Gate Leakage Current	I _{GSS}			±10	μΑ	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$
Gate Cut-off Voltage	$V_{GS(off)}$	0.5		1.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward Transfer Admittance *1	y _{fs}	25			S	$V_{DS} = 10 \text{ V}, I_D = 6.8 \text{ A}$
Drain to Source On-state Resistance *1	R _{DS(on)1}		3.4	4.3	mΩ	$V_{GS} = 8.0 \text{ V}, I_D = 13.5 \text{ A}$
	R _{DS(on)2}		3.9	4.8	mΩ	$V_{GS} = 4.5 \text{ V}, I_D = 13.5 \text{ A}$
	R _{DS(on)3}		5.4	9.9	mΩ	$V_{GS} = 2.5 \text{ V}, I_D = 6.8 \text{ A}$
Input Capacitance	C _{iss}		3610		pF	V _{DS} = 10 V,
Output Capacitance	Coss		1230		pF	$V_{GS} = 0 V$,
Reverse Transfer Capacitance	C _{rss}		1130		pF	f = 1 MHz
Turn-on Delay Time	t _{d(on)}		50		ns	$V_{DD} = 10 \text{ V}, I_D = 13.5 \text{ A},$
Rise Time	t _r		94		ns	$V_{GS} = 4.0 V,$
Turn-off Delay Time	t _{d(off)}		120		ns	$R_G = 10 \Omega$
Fall Time	t _f		120		ns	
Total Gate Charge	Q_G		37		nC	V _{DD} = 10 V,
Gate to Source Charge	Q _{GS}		7		nC	$V_{GS} = 4.0 V,$
Gate to Drain Charge	Q_{GD}		18		nC	I _D = 27 A
Body Diode Forward Voltage *1	$V_{F(S-D)}$		0.82		V	I _F = 27 A, V _{GS} = 0 V
Reverse Recovery Time	t _{rr}		73		ns	$I_F = 27 \text{ A}, V_{GS} = 0 \text{ V},$
Reverse Recovery Charge	Q _{rr}		70		nC	di/dt = 100 A/μs

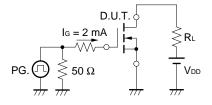
Note: *1. Pulsed

TEST CIRCUIT 1 SWITCHING TIME

PG. R_{G} $\tau = 1 \mu s$ Duty Cycle $\leq 1\%$

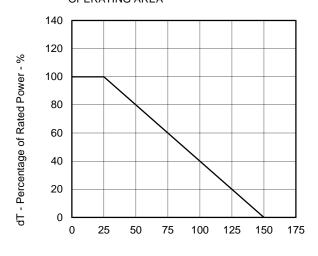


TEST CIRCUIT 2 GATE CHARGE



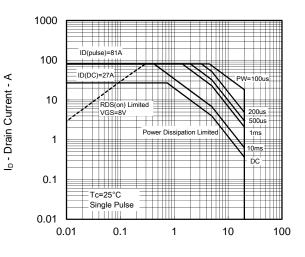
TYPICAL CHARACTERISTICS $(T_A = 25^{\circ}C)$

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



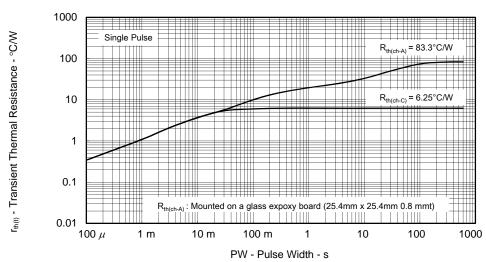
T_C - Case Temperature - °C

FORWARD BIAS SAFE OPERATING AREA

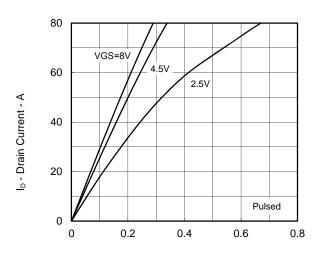


V_{DS} - Drain to Source Voltage - V

TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

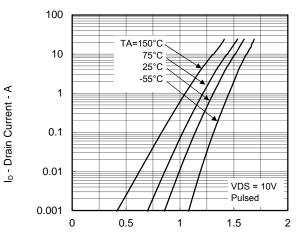


DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



 V_{DS} - Drain to Source Voltage - V

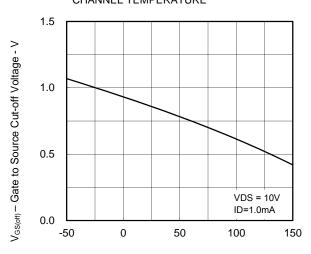
FORWARD TRANSFER CHARACTERISTICS



 V_{GS} - Gate to Source Voltage - V

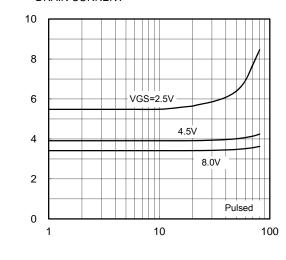
 $R_{\text{DS}(\text{on})}$ - Drain to Source On-state Resistance - $m\Omega$

GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



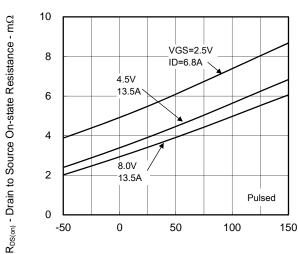
T_{ch} - Channel Temperature - °C

DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



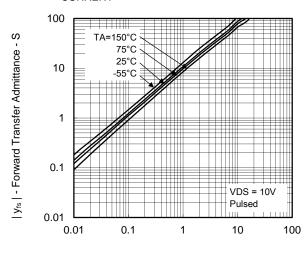
ID - Drain Current - A

DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



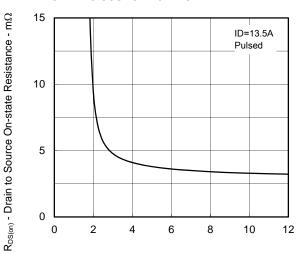
 T_{ch} - Channel Temperature - $\,^{\circ}C$

FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



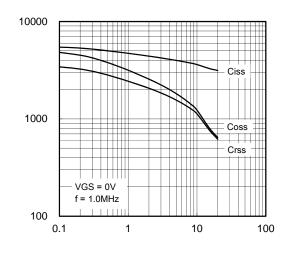
ID - Drain Current - A

DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



V_{GS} - Gate to Source Voltage - V

CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

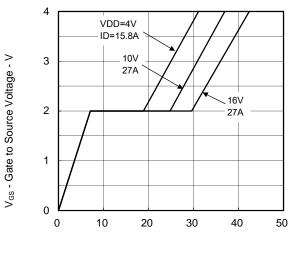


 V_{DS} - Drain to Source Voltage - V

Ciss, Coss, Crss - Capacitance - pF

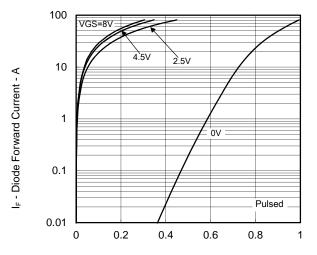
SWITCHING CHARACTERISTICS

DYNAMIC INPUT CHARACTERISTICS



Q_G - Gate Charge - nC

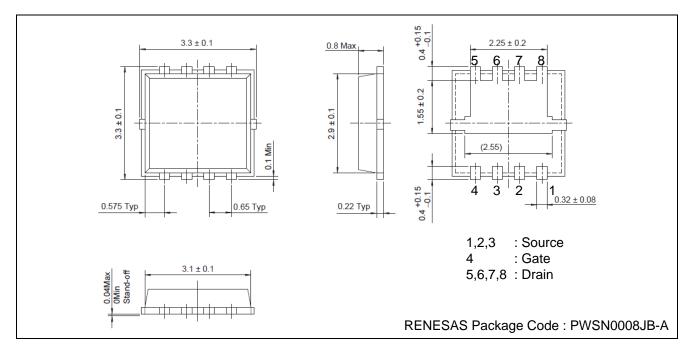
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



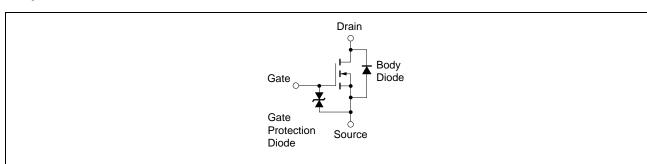
 $V_{F(S-D)}$ - Source to Drain Voltage - V

Package Drawings (Unit: mm)

HWSON-8



Equivalent Circuit



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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